

PRODUCT DESCRIPTION



Laird Tflex[™] HD80000 is the latest product in the High Deflection gap filler series. Tflex[™] HD80000 combines 6 W/mK thermal conductivity with superior pressure versus deflection characteristics. The combination will allow minimal stress on components while also yielding low thermal resistance. As a result, less mechanical and thermal stresses will be experienced within your device.

The Tflex HD80000 material is extremely soft, but also can be handled and applied manually without the need to add a fiberglass or other reinforcement layer, maintaining the superior thermal performance of the product.

FEATURES AND BENEFITS

- 6 W/mK thermal conductivity
- Low pressure versus deflection
- Excellent surface wetting for low contact resistance
- No fiberglass reinforcement
- Minimizes board and component stress
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

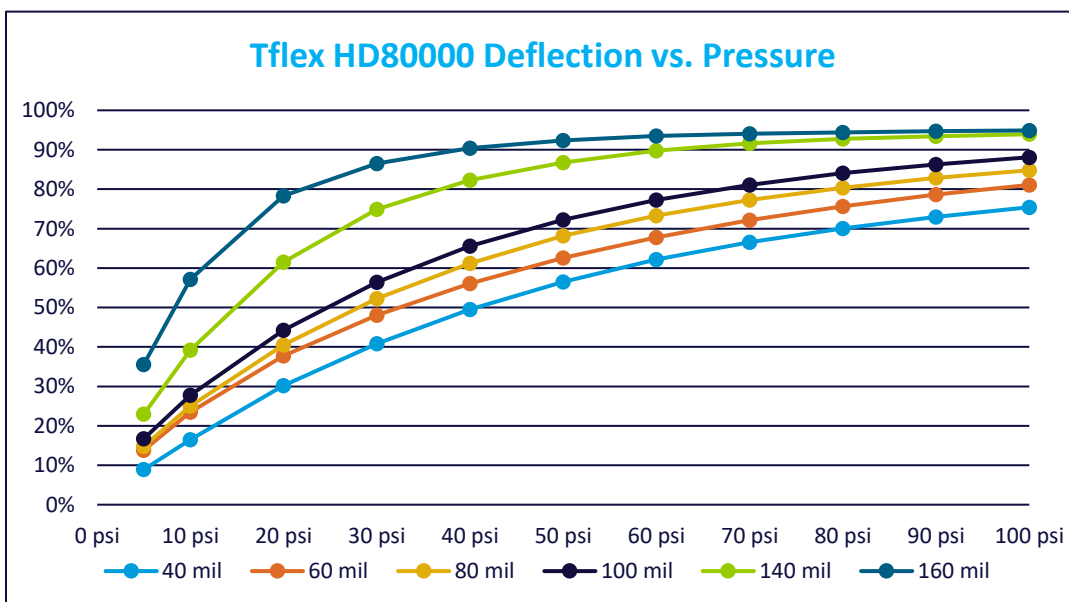
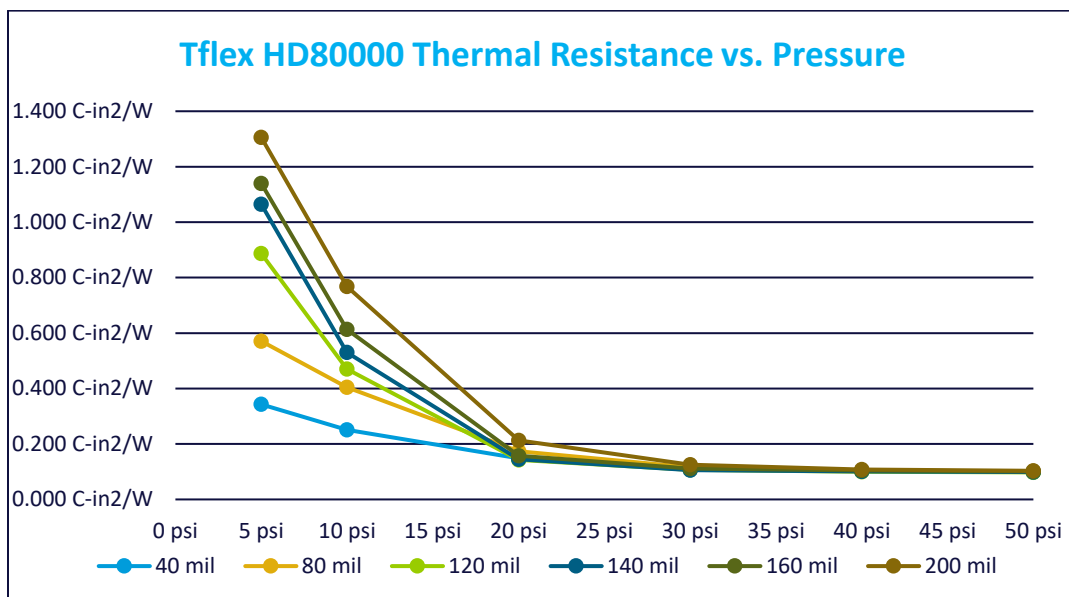
SPECIFICATIONS

TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	N/A
Color	Teal	Visual
Thickness Range	1 mm (0.040") - 5.0mm (0.20")	N/A
Thickness Tolerance	+/- 10%	N/A
Thermal Conductivity (W/mK)	6.0	Hot Disk
Density (g/cc)	3.3	Helium Pycnometer
Hardness (Shore 00, 3 sec)	40	ASTM D2240
Hardness (Shore 00, 30 sec)	32	ASTM D2240
Outgassing TML (weight %)	0.3	ASTM E595
Outgassing CVCM (weight %)	0.04	ASTM E595
Temperature Range	-40°C to 150°C	Laird Test Method
Rth@ 50 mils, 10 psi	0.330	ASTM D5470 (Modified)
Dielectric Constant @ 1 MHz	9	ASTM D150
UL Flammability Rating	V-0	UL 94
Volume Resistivity	1.06 x 10 ¹⁶	ASTM D257



Tflex™ HD80000 Series

Thermal Gap Filler



AVAILABILITY

STANDARD THICKNESSES

- 1.0 mm (0.040") to 5.0 mm (0.200") thick material available in 0.25mm (0.010") increments
- Available in standard sheet sizes of 9" x 9" or custom die cut parts

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. HD8xxxx indicates Tflex HD80000 product line with thickness in microns

EXAMPLES:

- Tflex™ HD81000 = 1000 microns / 0.040" thick Tflex™ HD80000 material

Tflex HD80000 A18003-00 Rev. D

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